

L Number	Hits	Search Text	DB	Time stamp
1	774608	radiate radiation radiated radiating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:03
2	472837	(control controlling controlled) with (terminal electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:35
3	4901	(radiate radiation radiated radiating) same ((control controlling controlled) with (terminal electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:05
4	591	(semiconductor chip die ic (integrated adj circuit)) same ((radiate radiation radiated radiating) same ((control controlling controlled) with (terminal electrode)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:20
5	40	(bump ball bga) and ((semiconductor chip die ic (integrated adj circuit)) same ((radiate radiation radiated radiating) same ((control controlling controlled) with (terminal electrode)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:21
6	1979	(semiconductor chip die ic (integrated adj circuit)) and ((radiate radiation radiated radiating) same ((control controlling controlled) with (terminal electrode)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:20
7	121	(bump ball bga) and ((semiconductor chip die ic (integrated adj circuit)) and ((radiate radiation radiated radiating) same ((control controlling controlled) with (terminal electrode)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:34
8	81	((bump ball bga) and ((semiconductor chip die ic (integrated adj circuit)) and ((radiate radiation radiated radiating) same ((control controlling controlled) with (terminal electrode)))) not ((bump ball bga) and ((semiconductor chip die ic (integrated adj circuit)) same ((radiate radiation radiated radiating) same ((control controlling controlled) with (terminal electrode))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:33
9	218	257/188	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:33
10	806	257/688	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:33
11	293	257/689	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:34
12	1221	257/188 257/688 257/689	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 08:34

13	437	(bump ball bga) and (257/188 257/688 257/689)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/08/06 08:35
14	189	(control controlling controlled) and ((bump ball bga) and (257/188 257/688 257/689))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/08/06 09:00
15	2	4620215.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/08/06 09:00
16	1		USPAT	2004/08/06 09:01
17	1		USPAT	2004/08/06 09:01
18	1		USPAT	2004/08/06 09:02
19	1		USPAT	2004/08/06 09:02
20	1		USPAT	2004/08/06 09:02
21	1		USPAT	2004/08/06 09:02
22	1		USPAT	2004/08/06 09:02
23	1		USPAT	2004/08/06 09:03
24	1		USPAT	2004/08/06 09:03
25	1		USPAT	2004/08/06 09:03
26	1		USPAT	2004/08/06 09:03
27	1		USPAT	2004/08/06 09:03
28	1		USPAT	2004/08/06 09:03